Silicon N-Channel MOS FET

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ADE-208-1321 (Z) 1st. Edition Mar. 2001

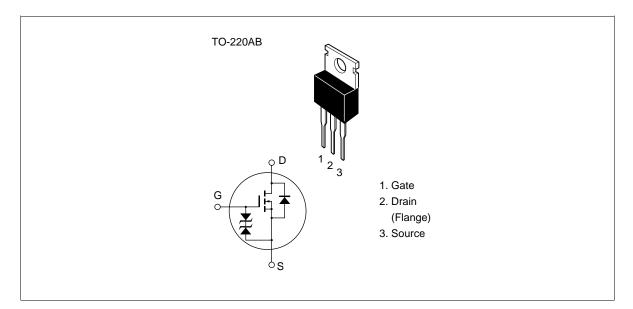
Application

High speed power switching

Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switchingregulator, DC-DC converter

Outline





Absolute Maximum Ratings (Ta = 25° C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V _{DSS}	900	V
Gate to source voltage	V _{GSS}	±30	V
Drain current	I _D	4	А
Drain peak current	L _{D(pulse)} *1	10	A
Body to drain diode reverse drain current	l _{DR}	4	A
Channel dissipation	Pch*2	60	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	-55 to +150	°C

Notes 1. PW \leq 10 μ s, duty cycle \leq 1 %

2. Value at Tc = 25 °C

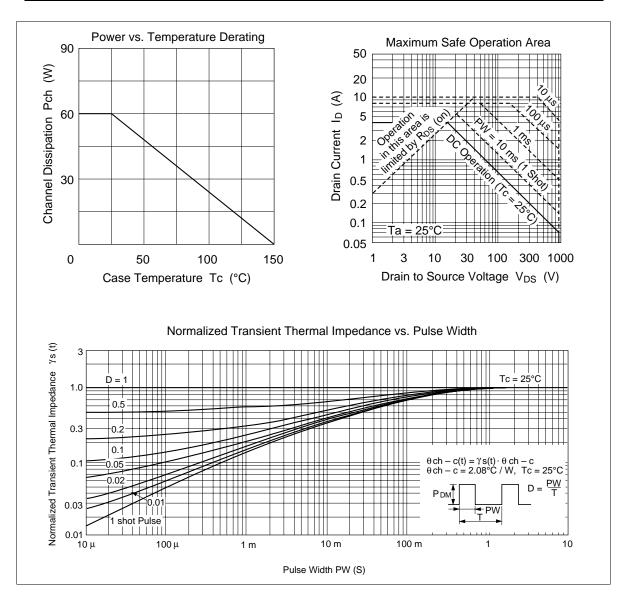
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Electrical Characteristics (Ta = 25° C)

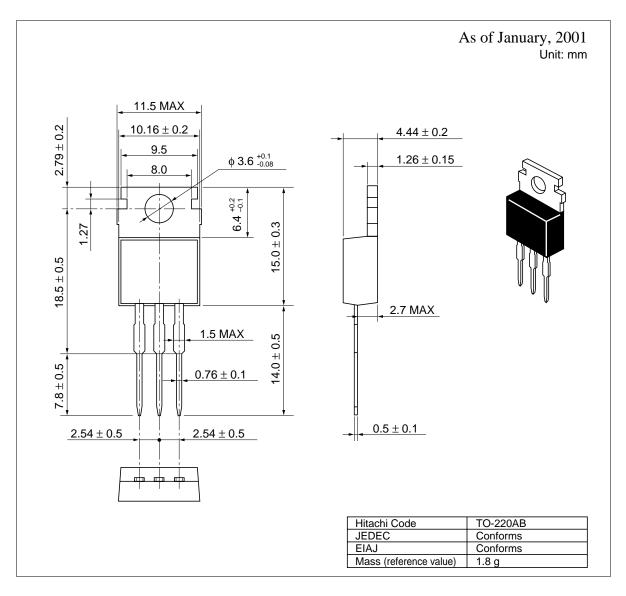
Item	Symbol	Min	Тур	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{\rm (BR)DSS}$	900	—	—	V	$I_{\rm D} = 10$ mA, $V_{\rm GS} = 0$
Gate to source breakdown voltage	$V_{\rm (BR)GSS}$	±30	—	—	V	$I_{G} = \pm 100 \ \mu A, \ V_{DS} = 0$
Gate to source leak current	I _{GSS}	_	_	±10	μΑ	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I _{DSS}	_	_	250	μΑ	$V_{\rm DS} = 720 \text{ V}, \text{ V}_{\rm GS} = 0$
Gate to source cutoff voltage	V _{GS(off)}	2.0	_	3.0	V	$I_{\rm D} = 1 \text{ mA}, V_{\rm DS} = 10 \text{ V}$
Static drain to source on state resistance	$R_{\text{DS(on)}}$		3.0	4.0	Ω	$I_{\rm D} = 2 \text{ A}$ $V_{\rm GS} = 10 \text{ V}^{*1}$
Forward transfer admittance	y _{fs}	1.7	2.7	—	S	$I_{\rm D} = 2 \text{ A}$ $V_{\rm DS} = 10 \text{ V}^{*1}$
Input capacitance	Ciss	_	740		pF	V _{DS} = 10 V
Output capacitance	Coss	_	305		pF	$V_{GS} = 0$
Reverse transfer capacitance	Crss	_	150		pF	f = 1 MHz
Turn-on delay time	t _{d(on)}	_	15	_	ns	I _D = 2 A
Rise time	t,	_	60	_	ns	V _{GS} = 10 V
Turn-off delay time	t _{d(off)}	_	100		ns	$R_L = 15 \Omega$
Fall time	t _f	_	80	_	ns	
Body to drain diode forward voltage	V_{DF}	—	0.9	—	V	$I_{F} = 4 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time	t _{rr}	—	800	—	ns	$I_F = 4 \text{ A}, V_{GS} = 0,$ $di_F / dt = 100 \text{ A} / \mu \text{s}$

Note 1. Pulse Test

See characteristic curves of 2SK1340



Package Dimensions



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